MBRD1035CTL

SWITCHMODE™ Schottky Power Rectifier

DPAK Power Surface Mount Package

. . . employing the Schottky Barrier principle in a large area metal−to−silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies, free wheeling diode and polarity protection diodes.

- Highly Stable Oxide Passivated Junction
- Guardring for Stress Protection
- Matched Dual Die Construction − May be Paralleled for High Current Output
- High dv/dt Capability
- Short Heat Sink Tap Manufactured − Not Sheared
- Very Low Forward Voltage Drop
- Epoxy Meets UL 94, V−0 @ 0.125 in
- Pb−Free Package May be Available. The G−Suffix Denotes a Pb−Free Lead Finish

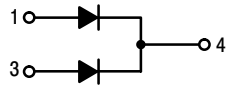
Mechanical Characteristics:

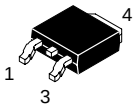
- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 75 units per plastic tube
- Available in 16 mm Tape and Reel, 2500 units per Reel, Add “T4’’ to Suffix part #
- Marking: B1035CL

ON Semiconductor®

http://onsemi.com

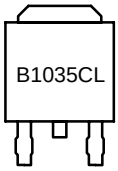
SCHOTTKY BARRIER RECTIFIER 10 AMPERES 35 VOLTS





DPAK
CASE 369A
PLASTIC

MARKING DIAGRAM



B1035CL = Device Code

ORDERING INFORMATION

Device	Package	Shipping†
MBRD1035CTL	DPAK	75 Units/Rail
MBRD1035CTLT4	DPAK	2500/Tape & Reel
MBRD1035CTLT4G	DPAK	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	35	Volts
Average Rectified Forward Current (At Rated V_R, T_C = 115°C)	Per Leg Per Package	I_O	5.0 10	Amps
Peak Repetitive Forward Current (At Rated V_R, Square Wave, 20 kHz, T_C = 115°C)	Per Leg	I_{FRM}	10	Amps
Non−Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	Per Package	I_{FSM}	50	Amps
Storage / Operating Case Temperature		T_{stg}, T_c	−55 to +125	°C
Operating Junction Temperature		T_J	−55 to +125	°C
Voltage Rate of Change (Rated V_R, T_J = 25°C)		dv/dt	10,000	V/μs

THERMAL CHARACTERISTICS

Thermal Resistance − Junction to Case	Per Leg	$R_{\theta JC}$	2.43	°C/W
Thermal Resistance − Junction to Ambient (Note 1)	Per Leg	$R_{\theta JA}$	68	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2) see Figure 2 I_F = 5 Amps, T_J = 25°C I_F = 5 Amps, T_J = 100°C I_F = 10 Amps, T_J = 25°C I_F = 10 Amps, T_J = 100°C	Per Leg	V_F	 0.47 0.41 0.56 0.55	Volts
Maximum Instantaneous Reverse Current (Note 2) see Figure 4 (V_R = 35 V, T_J = 25°C) (V_R = 35 V, T_J = 100°C) (V_R = 17.5 V, T_J = 25°C) (V_R = 17.5 V, T_J = 100°C)	Per Leg	I_R	 2.0 30 0.20 5.0	mA

1. Rating applies when using minimum pad size, FR4 PC Board
2. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

TYPICAL CHARACTERISTICS

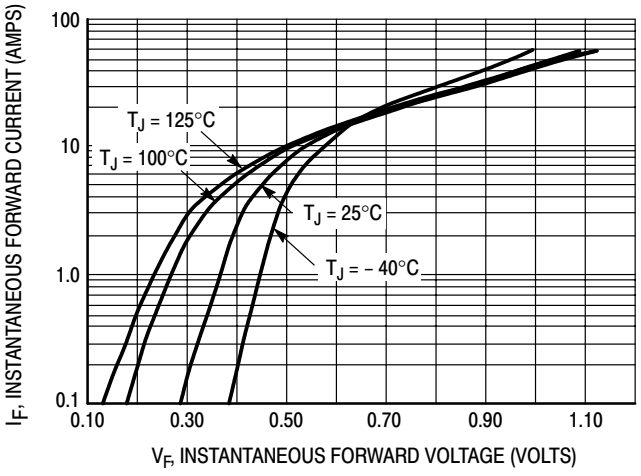


Figure 1. Typical Forward Voltage Per Leg

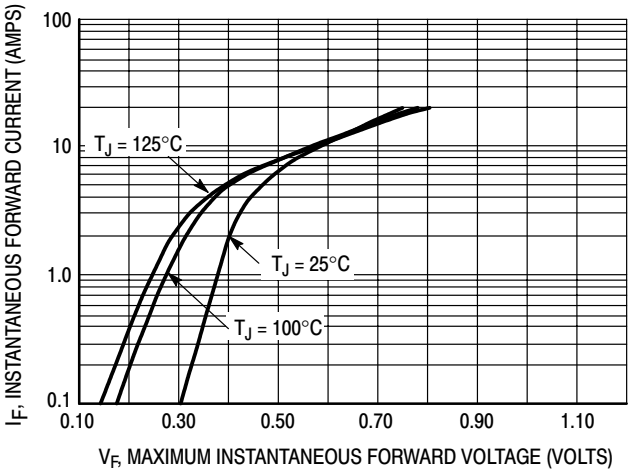


Figure 2. Maximum Forward Voltage Per Leg

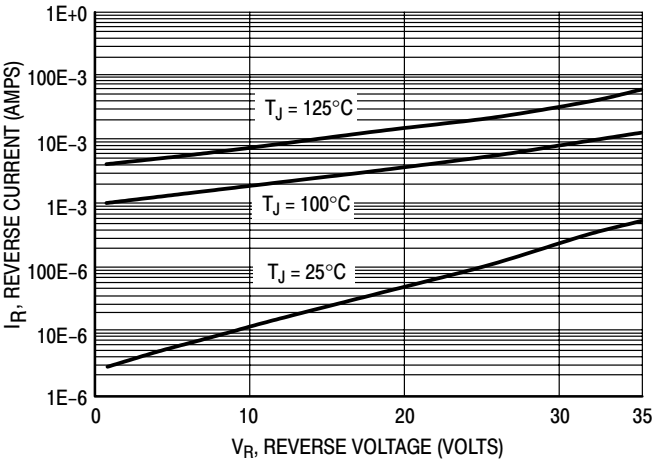


Figure 3. Typical Reverse Current Per Leg

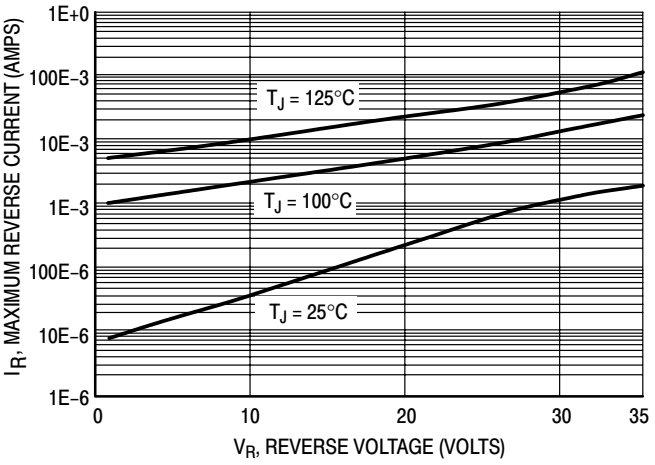


Figure 4. Maximum Reverse Current Per Leg

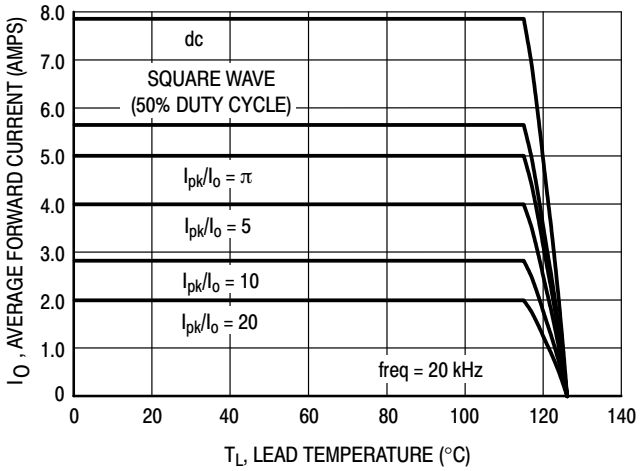


Figure 5. Current Derating Per Leg

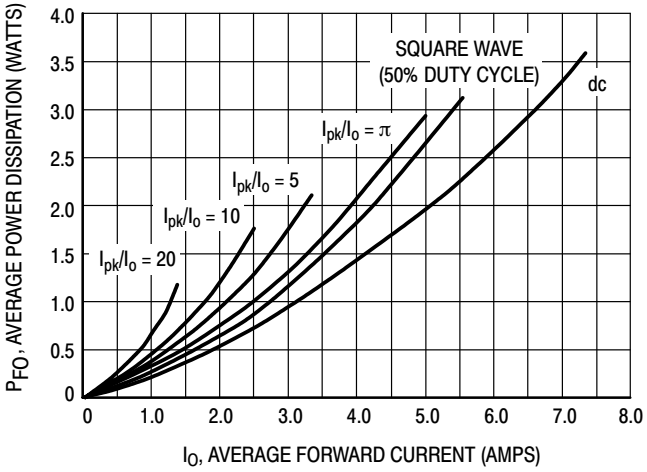


Figure 6. Forward Power Dissipation Per Leg

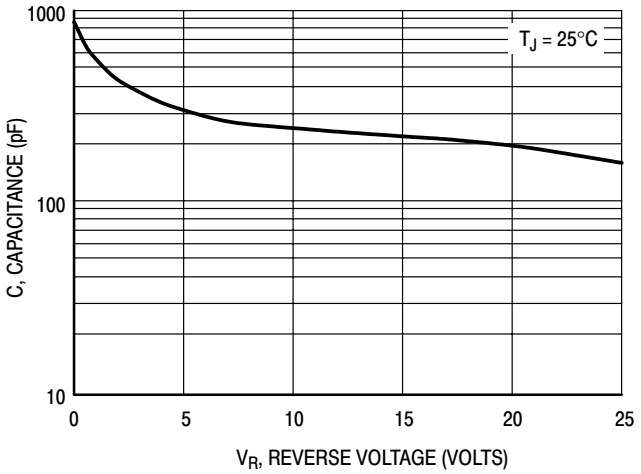


Figure 7. Capacitance Per Leg

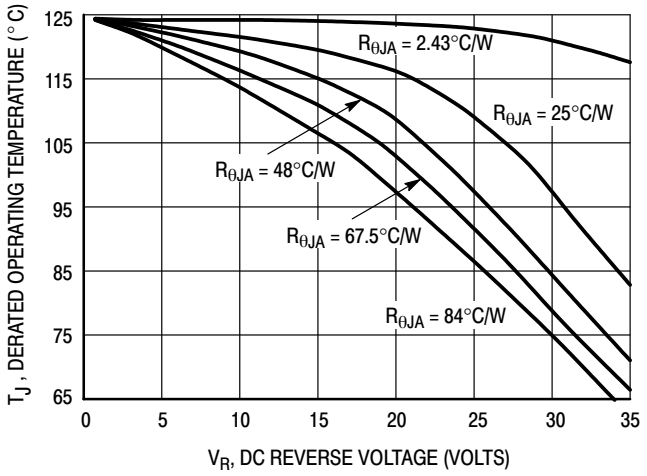


Figure 8. Typical Operating Temperature Derating Per Leg *

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where
r(t) = thermal impedance under given conditions,
Pf = forward power dissipation, and
Pr = reverse power dissipation
This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

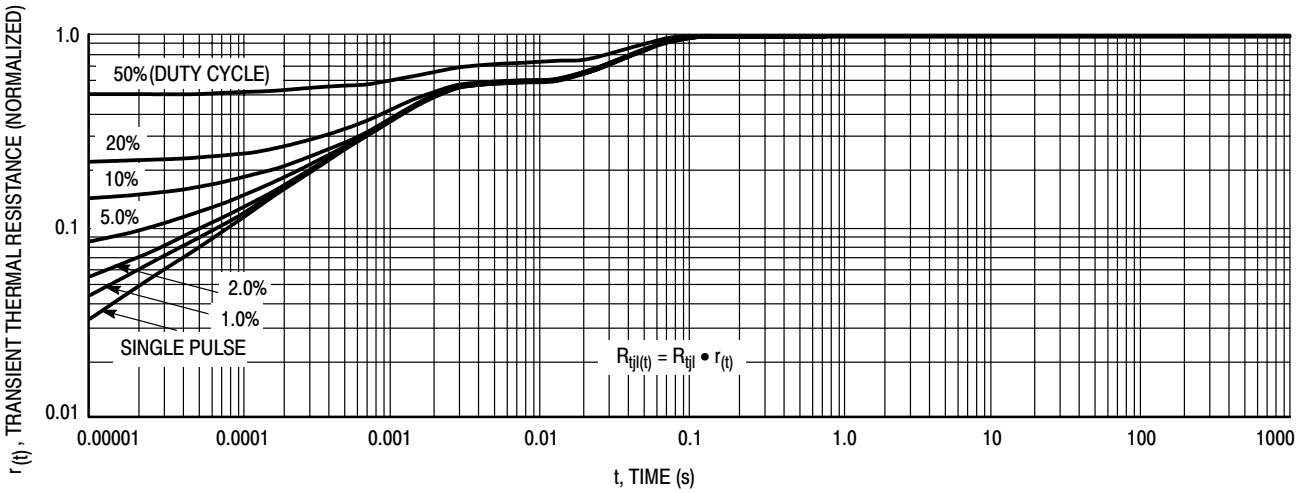


Figure 9. Thermal Response Junction to Case (Per Leg)

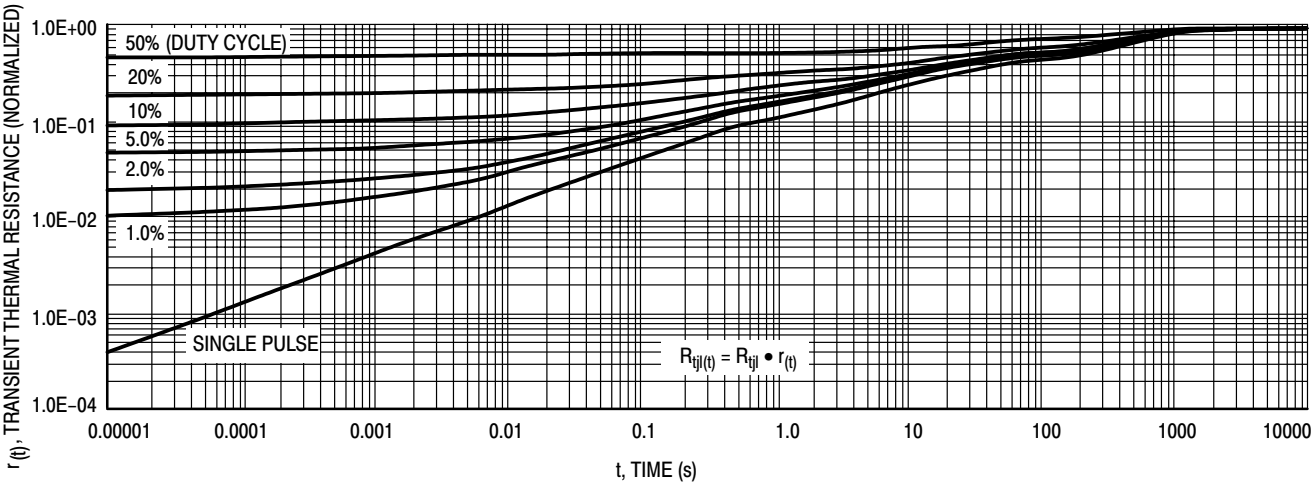
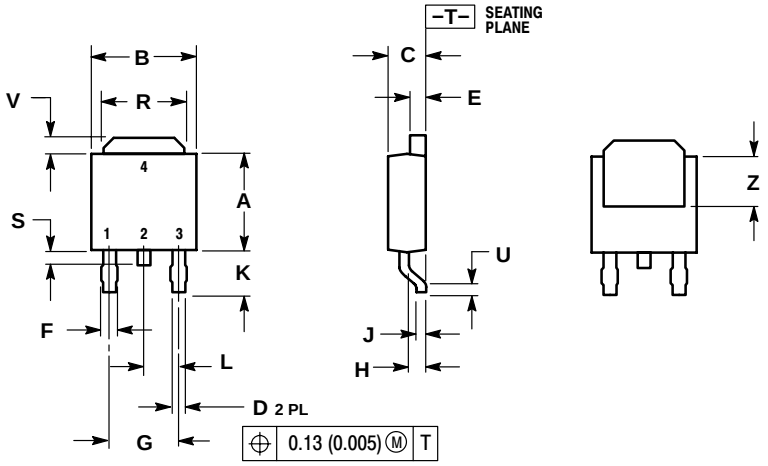


Figure 10. Thermal Response Junction to Ambient (Per Leg)

PACKAGE DIMENSIONS

DPAK
PLASTIC
CASE 369A−13
ISSUE AB

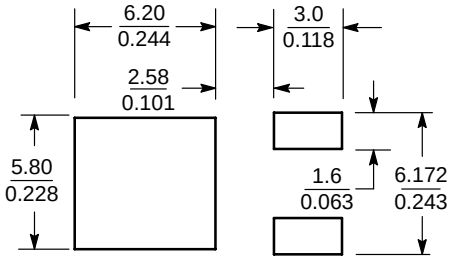


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	---	0.51	---
V	0.030	0.050	0.77	1.27
Z	0.138	---	3.51	---

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

SOLDERING FOOTPRINT*



SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

Figure 11. DPAK

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
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